## 507310541 05/31/2022

# **PATENT ASSIGNMENT COVER SHEET**

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT7357464

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	

#### **CONVEYING PARTY DATA**

Name	Execution Date
PO-HSIU HSIAO	05/30/2022
LIANG-WEI HUANG	05/30/2022

### **RECEIVING PARTY DATA**

Name:	REALTEK SEMICONDUCTOR CORP.
Street Address:	NO.2, INNOVATION ROAD II, HSINCHU SCIENCE PARK,
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300

## **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	17828544

## **CORRESPONDENCE DATA**

**Fax Number:** (703)574-5876

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

**Phone:** 17032685992

Email: zhuoxu83@gmail.com

Correspondent Name: LI&CAI INTELLECTUAL PROPERTY(USA) OFFICE

Address Line 1: 3057 NUTLEY STREET, SUITE 818

Address Line 4: FAIRFAX, VIRGINIA 22031

ATTORNEY DOCKET NUMBER:	109P001478US
NAME OF SUBMITTER:	ZHUO XU
SIGNATURE:	/ZHUO XU/
DATE SIGNED:	05/31/2022

### **Total Attachments: 2**

source=109P001478US-ASSIGNMENT#page1.tif source=109P001478US-ASSIGNMENT#page2.tif

PATENT 507310541 REEL: 060056 FRAME: 0877

## ASSIGNMENT DEED

# Attorney docket No. 109P001478US

METHOD FOR CANCELLING RADIO FREQUENCY INTERFEREN AND COMMUNICATION SYSTEM THEREOF The PATENT RIGHTS referred to in this agreement are:  (Check one)  a Patent Application for this invention, executed by the ASSIGNOR(S) concurrently with this Assigner and Patent Application Serial No.  U.S. Patent Application Serial No.  The PATENT RIGHTS assigned under this agreement are:  (Check One)  Worldwide Patent rights. In this case, the assignee shall have the right to claim the benefit of the of any U.S. Patent Application identified above.  IWE believe that IWE am/are the original inventor(s) of a claimed invention in the application. The above-identified Application was made or authorized by me/us.  IWE hereby acknowledge that any will false statements made in this Assignment is punishable under 1001 by fine or imprisonment of not more than five (5) years, or both.  The ASSIGNOR(S) referred to in this agreement is (or are):  (Full name of sole or first assignor)  (Full name of sole or first assignor, if any)  LIANG-WEI HUANG  (FAMILY NAME: HUANG)  (Address)  NO.2, INNOVATION ROAD II, HSINCHU SCIENCE PARK, HSINCHU 300, TAIWAN, R.O.C.  (Full name of third joint assignor, if any)  (FAMILY NAME: HUANG)  (Address)  Additional assignors are being named on separately numbered sheets attached hereto.  The sole or first ASSIGNEE(S) referred to in this agreement is (or are):  (Name of Assignee)  NO.2, INNOVATION ROAD II, HSINCHU SCIENCE PARK, HSINCHU 300, TAIWAN, R.O.C.  (Name of Assignee)  NO.2, INNOVATION ROAD II, HSINCHU SCIENCE PARK, HSINCHU 300, TAIWAN, R.O.C.	CE
The PATENT RIGHTS referred to in this agreement are:  (Check one)  a Patent Application for this invention, executed by the ASSIGNOR(S) concurrently with this Assignation of the patent Application Serial No	خدب
(Check one)  a Patent Application for this invention, executed by the ASSIGNOR(S) concurrently with this Assignance and Patent Application Serial No	
U.S. Patent Application Serial No	
U.S. Patent Application Serial No	nment
The PATENT RIGHTS assigned under this agreement are:  (Check One)  U.S. Patent rights only  worldwide Patent rights. In this case, the assignee shall have the right to claim the benefit of the total under the properties of any U.S. Patent Application identified above.  IME believe that I/WE am/are the original inventor(s) of a claimed invention in the application. The above-identified Application was made or authorized by me/us.  IME hereby acknowledge that any will false statements made in this Assignment is punishable under 1001 by fine or imprisonment of not more than five (5) years, or both.  The ASSIGNOR(S) referred to in this agreement is (or are):  (Full name of sole or first assignor) PO-HSIU HSIAO (FAMILY NAME: HSIAO)  (Address) NO.2. INNOVATION ROAD II, HSINCHU SCIENCE PARK, HSINCHU 300, TAIWAN, R.O.C.  (Full name of second joint assignor, if any) LIANG-WEI HUANG (FAMILY NAME: HUANG)  (Address) NO.2, INNOVATION ROAD II, HSINCHU SCIENCE PARK, HSINCHU 300, TAIWAN, R.O.C.  (Full name of third joint assignor, if any) (FAMILY NAME: HUANG)  (Address) NO.2, INNOVATION ROAD II, HSINCHU SCIENCE PARK, HSINCHU 300, TAIWAN, R.O.C.  (Full name of third joint assignor, if any) (FAMILY NAME: HUANG)  (Address) REALTEK SEMICONDUCTOR CORP.	
The PATENT RIGHTS assigned under this agreement are:  (Check One)  U.S. Patent rights only  worldwide Patent rights. In this case, the assignee shall have the right to claim the benefit of the of any U.S. Patent Application identified above.  I.W. Delieve that I.W. am/are the original inventor(s) of a claimed invention in the application. The above-identified Application was made or authorized by me/us.  I.W. hereby acknowledge that any will false statements made in this Assignment is punishable under 1001 by fine or imprisonment of not more than five (5) years, or both.  The ASSIGNOR(S) referred to in this agreement is (or are):  (Full name of sole or first assignor) PO-HSIU HSIAO (FAMILY NAME: HSIAO)  NO.2, INNOVATION ROAD II, HSINCHU SCIENCE PARK, HSINCHU 300, TAIWAN, R.O.C.  (Full name of second joint assignor, if any) LIANG-WEI HUANG (FAMILY NAME: HUANG)  NO.2, INNOVATION ROAD II, HSINCHU SCIENCE PARK, HSINCHU 300, TAIWAN, R.O.C.  (Full name of third joint assignor, if any) (FAMILY NAME: HUANG)  Address)  Additional assignors are being named on separately numbered sheets attached hereto.  The sole or first ASSIGNEE(S) referred to in this agreement is (or are):  (Name of Assignee) REALTEK SEMICONDUCTOR CORP.	
(Check One)  U.S. Patent rights only  worldwide Patent rights. In this case, the assignee shall have the right to claim the benefit of the formal of any U.S. Patent Application identified above.  I/WE believe that I/WE am/are the original inventor(s) of a claimed invention in the application. The above-identified Application was made or authorized by me/us.  I/WE hereby acknowledge that any will false statements made in this Assignment is punishable under 1001 by fine or imprisonment of not more than five (5) years, or both.  The ASSIGNOR(S) referred to in this agreement is (or are):  (Full name of sole or first assignor) PO-HSIU HSIAO (FAMILY NAME: HSIAO)  NO.2, INNOVATION ROAD II, HSINCHU SCIENCE PARK, HSINCHU 300, TAIWAN, R.O.C.  (Full name of second joint assignor, if any) LIANG-WEI HUANG (FAMILY NAME: HUANG)  (Address) NO.2, INNOVATION ROAD II, HSINCHU SCIENCE PARK, HSINCHU 300, TAIWAN, R.O.C.  (Full name of third joint assignor, if any) (FAMILY NAME: HUANG)  Additional assignors are being named on separately numbered sheets attached hereto.  The sole or first ASSIGNEE(S) referred to in this agreement is (or are):  (Name of Assignee) REALTEK SEMICONDUCTOR CORP.	
(Check One)  ■ U.S. Patent rights only  □ worldwide Patent rights. In this case, the assignee shall have the right to claim the benefit of the of any U.S. Patent Application identified above.  I/WE believe that I/WE am/are the original inventor(s) of a claimed invention in the application.  The above-identified Application was made or authorized by me/us.  I/WE hereby acknowledge that any will false statements made in this Assignment is punishable under 1001 by fine or imprisonment of not more than five (5) years, or both.  The ASSIGNOR(S) referred to in this agreement is (or are):  (Full name of sole or first assignor) PO-HSIU HSIAO (FAMILY NAME: HSIAO)  (Address) NO.2, INNOVATION ROAD II, HSINCHU SCIENCE PARK, HSINCHU 300, TAIWAN, R.O.C.  (Full name of second joint assignor, if any) LIANG-WEI HUANG (FAMILY NAME: HUANG)  (Address) NO.2, INNOVATION ROAD II, HSINCHU SCIENCE PARK, HSINCHU 300, TAIWAN, R.O.C.  (Full name of third joint assignor, if any) (FAMILY NAME: HUANG)  (Address) Additional assignors are being named on separately numbered sheets attached hereto.  The sole or first ASSIGNEE(S) referred to in this agreement is (or are):  (Name of Assignee) REALTEK SEMICONDUCTOR CORP.	
worldwide Patent rights. In this case, the assignee shall have the right to claim the benefit of the of any U.S. Patent Application identified above.  IWE believe that IWE am/are the original inventor(s) of a claimed invention in the application. The above-identified Application was made or authorized by me/us.  IWE hereby acknowledge that any will false statements made in this Assignment is punishable under 1001 by fine or imprisonment of not more than five (5) years, or both.  The ASSIGNOR(S) referred to in this agreement is (or are):  (Full name of sole or first assignor) PO-HSIU HSIAO (FAMILY NAME: HSIAO)  NO.2, INNOVATION ROAD II, HSINCHU SCIENCE PARK, HSINCHU 300, TAIWAN, R.O.C.  (Full name of second joint assignor, if any) LIANG-WEI HUANG (FAMILY NAME: HUANG)  (Address) NO.2, INNOVATION ROAD II, HSINCHU SCIENCE PARK, HSINCHU 300, TAIWAN, R.O.C.  (Full name of third joint assignor, if any) (FAMILY NAME: HUANG)  Address) Additional assignors are being named on separately numbered sheets attached hereto.  The sole or first ASSIGNEE(S) referred to in this agreement is (or are):  (Name of Assignee) REALTEK SEMICONDUCTOR CORP.	
of any U.S. Patent Application identified above.  IWE believe that IWE am/are the original inventor(s) of a claimed invention in the application.  The above-identified Application was made or authorized by me/us.  IWE hereby acknowledge that any will false statements made in this Assignment is punishable under 1001 by fine or imprisonment of not more than five (5) years, or both.  The ASSIGNOR(S) referred to in this agreement is (or are):  (Full name of sole or first assignor) PO-HSIU HSIAO (FAMILY NAME: HSIAO)  (Address) NO.2. INNOVATION ROAD II, HSINCHU SCIENCE PARK, HSINCHU 300, TAIWAN, R.O.C.  (Full name of second joint assignor, if any) LIANG-WEI HUANG (FAMILY NAME: HUANG)  (Address) NO.2. INNOVATION ROAD II. HSINCHU SCIENCE PARK, HSINCHU 300, TAIWAN, R.O.C.  (Full name of third joint assignor, if any) (FAMILY NAME: HUANG)  Address)  Additional assignors are being named on separately numbered sheets attached hereto.  The sole or first ASSIGNEE(S) referred to in this agreement is (or are):  (Name of Assignee) REALTEK SEMICONDUCTOR CORP.	
of any U.S. Patent Application identified above.  IWE believe that IWE am/are the original inventor(s) of a claimed invention in the application.  The above-identified Application was made or authorized by me/us.  IWE hereby acknowledge that any will false statements made in this Assignment is punishable under 1001 by fine or imprisonment of not more than five (5) years, or both.  The ASSIGNOR(S) referred to in this agreement is (or are):  (Full name of sole or first assignor) PO-HSIU HSIAO (FAMILY NAME: HSIAO)  (Address) NO.2. INNOVATION ROAD II, HSINCHU SCIENCE PARK, HSINCHU 300, TAIWAN, R.O.C.  (Full name of second joint assignor, if any) LIANG-WEI HUANG (FAMILY NAME: HUANG)  (Address) NO.2. INNOVATION ROAD II. HSINCHU SCIENCE PARK, HSINCHU 300, TAIWAN, R.O.C.  (Full name of third joint assignor, if any) (FAMILY NAME: HUANG)  Address)  Additional assignors are being named on separately numbered sheets attached hereto.  The sole or first ASSIGNEE(S) referred to in this agreement is (or are):  (Name of Assignee) REALTEK SEMICONDUCTOR CORP.	ilina da
IWE believe that I/WE am/are the original inventor(s) of a claimed invention in the application.  The above-identified Application was made or authorized by me/us.  I/WE hereby acknowledge that any will false statements made in this Assignment is punishable under 1001 by fine or imprisonment of not more than five (5) years, or both.  The ASSIGNOR(S) referred to in this agreement is (or are):  (Full name of sole or first assignor) PO-HSIU HSIAO (FAMILY NAME: HSIAO)  (Address) NO.2. INNOVATION ROAD II, HSINCHU SCIENCE PARK, HSINCHU 300, TAIWAN, R.O.C.  (Full name of second joint assignor, if any) LIANG-WEI HUANG (FAMILY NAME: HUANG)  (Address) NO.2. INNOVATION ROAD II. HSINCHU SCIENCE PARK, HSINCHU 300, TAIWAN, R.O.C.  (Full name of third joint assignor, if any) (FAMILY NAME: HUANG)  Additional assignors are being named on separately numbered sheets attached hereto.  The sole or first ASSIGNEE(S) referred to in this agreement is (or are):  (Name of Assignee) REALTEK SEMICONDUCTOR CORP.	mig ga
The above-identified Application was made or authorized by me/us.  !/WE hereby acknowledge that any will false statements made in this Assignment is punishable under 1001 by fine or imprisonment of not more than five (5) years, or both.  The ASSIGNOR(S) referred to in this agreement is (or are):  (Full name of sole or first assignor) PO-HSIU HSIAO (FAMILY NAME: HSIAO)  (Address) NO.2. INNOVATION ROAD II, HSINCHU SCIENCE PARK, HSINCHU 300, TAIWAN, R.O.C.  (Full name of second joint assignor, if any) LIANG-WEI HUANG (FAMILY NAME: HUANG)  (Address) NO.2, INNOVATION ROAD II, HSINCHU SCIENCE PARK, HSINCHU 300, TAIWAN, R.O.C.  (Full name of third joint assignor, if any) (FAMILY NAME: MAME)  (Address) Additional assignors are being named on separately numbered sheets attached hereto.  The sole or first ASSIGNEE(S) referred to in this agreement is (or are):  (Name of Assignee) REALTEK SEMICONDUCTOR CORP.	
I/WE hereby acknowledge that any will false statements made in this Assignment is punishable under 1001 by fine or imprisonment of not more than five (5) years, or both.  The ASSIGNOR(S) referred to in this agreement is (or are):  (Full name of sole or first assignor) PO-HSIU HSIAO (FAMILY NAME: HSIAO)  (Address) NO.2. INNOVATION ROAD II. HSINCHU SCIENCE PARK, HSINCHU 300, TAIWAN, R.O.C.  (Full name of second joint assignor, if any) LIANG-WEI HUANG (FAMILY NAME: HUANG)  (Address) NO.2. INNOVATION ROAD II. HSINCHU SCIENCE PARK, HSINCHU 300, TAIWAN, R.O.C.  (Full name of third joint assignor, if any) (FAMILY NAME:  (Address) Additional assignors are being named on separately numbered sheets attached hereto.  The sole or first ASSIGNEE(S) referred to in this agreement is (or are):  (Name of Assignee) REALTEK SEMICONDUCTOR CORP.	
The ASSIGNOR(S) referred to in this agreement is (or are):  (Full name of sole or first assignor) PO-HSIU HSIAO (FAMILY NAME: HSIAO)  (Address) NO.2, INNOVATION ROAD II, HSINCHU SCIENCE PARK, HSINCHU 300, TAIWAN, R.O.C.  (Full name of second joint assignor, if any) LIANG-WEI HUANG (FAMILY NAME: HUANG)  (Address) NO.2, INNOVATION ROAD II. HSINCHU SCIENCE PARK, HSINCHU 300, TAIWAN, R.O.C.  (Full name of third joint assignor, if any) (FAMILY NAME: HUANG)  (Address) (FAMILY NAME: PAMILY NAME: PAMIL	ia usc
The ASSIGNOR(S) referred to in this agreement is (or are):  (Full name of sole or first assignor) PO-HSIU HSIAO (FAMILY NAME: HSIAO)  (Address) NO.2, INNOVATION ROAD II, HSINCHU SCIENCE PARK, HSINCHU 300, TAIWAN, R.O.C.  (Full name of second joint assignor, if any) LIANG-WEI HUANG (FAMILY NAME: HUANG)  (Address) NO.2, INNOVATION ROAD II, HSINCHU SCIENCE PARK, HSINCHU 300, TAIWAN, R.O.C.  (Full name of third joint assignor, if any) (FAMILY NAME:  Address)  Address)  Address)  Additional assignors are being named on separately numbered sheets attached hereto.  The sole or first ASSIGNEE(S) referred to in this agreement is (or are):  (Name of Assignee) REALTEK SEMICONDUCTOR CORP.	
(Full name of sole or first assignor) PO-HSIU HSIAO (FAMILY NAME: HSIAO)  (Address) NO.2. INNOVATION ROAD II, HSINCHU SCIENCE PARK, HSINCHU 300, TAIWAN, R.O.C.  (Full name of second joint assignor, if any) LIANG-WEI HUANG (FAMILY NAME: HUANG)  (Address) NO.2. INNOVATION ROAD II. HSINCHU SCIENCE PARK, HSINCHU 300, TAIWAN, R.O.C.  (Full name of third joint assignor, if any) (FAMILY NAME:  Address)  Address)  Address  Address  Address  Address  REALTEK SEMICONDUCTOR CORP.	
Address)  NO.2. INNOVATION ROAD II, HSINCHU SCIENCE PARK, HSINCHU 300, TAIWAN, R.O.C.  (Full name of second joint assignor, if any)  LIANG-WEI HUANG (FAMILY NAME: HUANG)  NO.2. INNOVATION ROAD II. HSINCHU SCIENCE PARK, HSINCHU 300, TAIWAN, R.O.C.  (Full name of third joint assignor, if any)  (FAMILY NAME:  Address)  Address)  Additional assignors are being named on separately numbered sheets attached hereto.  The sole or first ASSIGNEE(S) referred to in this agreement is (or are):  (Name of Assignee)  REALTEK SEMICONDUCTOR CORP.	
Address) NO.2, INNOVATION ROAD II, HSINCHU SCIENCE PARK, HSINCHU 300, TAIWAN, R.O.C.  (Full name of second joint assignor, if any) LIANG-WEI HUANG (FAMILY NAME: HUANG)  NO.2, INNOVATION ROAD II. HSINCHU SCIENCE PARK, HSINCHU 300, TAIWAN, R.O.C.  (Full name of third joint assignor, if any) (FAMILY NAME:  Address)  Address)  Address  The sole or first ASSIGNEE(S) referred to in this agreement is (or are):  (Name of Assignee) REALTEK SEMICONDUCTOR CORP.	
(Full name of second joint assignor, if any)  LIANG-WEI HUANG (FAMILY NAME: HUANG)  (Address)  NO.2, INNOVATION ROAD II. HSINCHU SCIENCE PARK, HSINCHU 300, TAIWAN, R.O.C.  (Full name of third joint assignor, if any)  (FAMILY NAME:  Address)  Additional assignors are being named on separately numbered sheets attached hereto.  The sole or first ASSIGNEE(S) referred to in this agreement is (or are):  (Name of Assignee)  REALTEK SEMICONDUCTOR CORP.	
(Address) NO.2, INNOVATION ROAD II, HSINCHU SCIENCE PARK, HSINCHU 300, TAIWAN, R.O.C.  (Full name of third joint assignor, if any) (FAMILY NAME:  (Address)  Additional assignors are being named on separately numbered sheets attached hereto.  The sole or first ASSIGNEE(S) referred to in this agreement is (or are):  (Name of Assignee) REALTEK SEMICONDUCTOR CORP.	
(Address) NO.2, INNOVATION ROAD II, HSINCHU SCIENCE PARK, HSINCHU 300, TAIWAN, R.O.C.  (Full name of third joint assignor, if any) (FAMILY NAME:  (Address)  Additional assignors are being named on separately numbered sheets attached hereto.  The sole or first ASSIGNEE(S) referred to in this agreement is (or are):  (Name of Assignee) REALTEK SEMICONDUCTOR CORP.	
(Full name of third joint assignor, if any) (FAMILY NAME:  (Address)  Additional assignors are being named on separately numbered sheets attached hereto.  The sole or first ASSIGNEE(S) referred to in this agreement is (or are):  (Name of Assignee) REALTEK SEMICONDUCTOR CORP.	
Address)  Additional assignors are being named on separately numbered sheets attached hereto.  The sole or first ASSIGNEE(S) referred to in this agreement is (or are):  (Name of Assignee) REALTEK SEMICONDUCTOR CORP.	
(Address)  Additional assignors are being named on separately numbered sheets attached hereto.  The sole or first ASSIGNEE(S) referred to in this agreement is (or are):  (Name of Assignee) REALTEK SEMICONDUCTOR CORP.	`
Additional assignors are being named on separately numbered sheets attached hereto.  The sole or first ASSIGNEE(S) referred to in this agreement is (or are):  (Name of Assignee)REALTEK SEMICONDUCTOR CORP.	
The sole or first ASSIGNEE(S) referred to in this agreement is (or are):  (Name of Assignee) REALTEK SEMICONDUCTOR CORP.	
The sole or first ASSIGNEE(S) referred to in this agreement is (or are):  (Name of Assignee)REALTEK SEMICONDUCTOR CORP.	***************************************
(Name of Assignee) REALTEK SEMICONDUCTOR CORP.	
(Name of Assignee) REALTEK SEMICONDUCTOR CORP.	
(Address of Assignee) NO.2, INNOVATION ROAD II, HSINCHU SCIENCE PARK, HSINCHU 300, TAIWAN, R	
	O.C.
The sole or first ASSIGNEE is: (Check One)	
an individual	
☐a partnership	
■a Corporation ofTAIWAN, R.O.C. (State or Country)	
(Source of Source )	

The second ASSIGNEE(S) (if any) referred to in this agreement is (or are);

109A-240US - 109P001478US

Page 1 of 2

(10019100)			······································
(Address of Assignee)			· · · · · · · · · · · · · · · · · · ·
The second ASSIGNEE is: (CI	neck One)		
	individual		
	partnership		
	Corporation of	(State or	Country)
Additional assignees are be	eing named on separately r	numbered sheets attach	ned hereto.
The ASSIGNOR(S)	in consideration of \$1.0	0 paid by each ASS	SIGNEE, and other good and valuable
			the following to each ASSIGNEE; their
successors and assigns:			
the full and exclusive	right to the invention;		
an equal interest in a	and to the entire right, title,	and interest in and to th	e PATENT RIGHTS in the invention, and
	n-part, divisional, re-issue,	and re-examination pa	tents and patent applications relating to
the PATENT RIGHTS; and			
	the second secon		preign applications for this invention.  ASSIGNOR(S) hereby authorize(s) and
			the ASSIGNEE(S) as the ASSIGNEE(S)
			enjoyment of said ASSIGNEE(S), their
successors and assigns.			
Further, the ASSIGN	OR(S) agree(s) to commu	nicate to said ASSIGN	EE(S), or their representatives, any facts
known to the ASSIGNOR(S) re	specting said invention, an	d testify in any legal pro	oceedings, sign all lawful papers, execute
			ations, execute all necessary assignment
			make all rightful oaths, and generally do
protection for said invention.	nie to aid said Assignee:	(S), their successors ar	nd assigns, to obtain and enforce proper
I/WE hereby give our Attorney	authorization to insert the	Serial Number and fili	ing date of the above-referenced Patent
Application when known.			
	PO-HSIU HSIAO	(FAMILY NAME: H	SIAO)
On note	1241		
PO-HSIU	HOLAN		2022/05/30
(Signature of sole	Or first assignor)	No. of the Art of the	(Date)
	LIANG-WEI HUANG	OT ARRUS V AVARATES IN	IANG
		(FAMILY NAME: HI	JANG)
Liang-We	Huana		2022/05/30
(Signature of sec	cond assignor)		2022/05/30 (Cate)
			Ç,
		(FAMILY NAME:	) · · · · · · · · ·
en de la companie de			
(Signature of third	assignor)		(D83e)
109A-240HS - 109P001478	TIC		

Page 2 of 2

PATENT REEL: 060056 FRAME: 0879